ABSTRACT OF THE DISCLOSURE

A semiconductor device comprises a plurality of bump electrodes at least to one surface. A circuit substrate is formed with a laminate structure having an inner layer circuit and a mounting pad is formed on the substrate. The mounting pad has a concave portion and the bottom of the concave portion is in contact with the inner layer circuit. Further, an sealing resin is provided on the substrate. The bump electrode and the concave portion of the mounting pad are opposed, and the bump electrode is pressed to the bottom of the concave portion of the mounting pad, thereby deforming the pointed shape portion at the top end of the bump electrode. By the deformation the pointed shape portion, the contact portion between the bump electrode and the mounting pad is gradually enlarged from a point to a plane. After deforming the bump electrode by a predetermined amount, the sealing resin is hardened and the semiconductor device is mounted on a substrate.